Product data sheet

1 Product profile

1.1 General description

General-purpose PIN diode in an SOD523 ultra-small SMD plastic package.

1.2 Features and benefits

- Low diode capacitance
- · Low diode forward resistance
- AEC-Q101 qualified

1.3 Applications

General RF applications



General purpose PIN diode

2 Pinning information

Table 1. Discrete pinning

| Pin | Description | Simplified outline | Graphic symbol |
|-----|-------------|--------------------|-------------------------|
| 1 | cathode | | 1.4 |
| 2 | anode | 1 2 | - ├ √- sym006 |
| | | Top view | |

3 Ordering information

Table 2. Ordering information

| Type number | Package | | | |
|-------------|---------|--|---------|--|
| | Name | Description | Version | |
| BAP51-02 | - | plastic surface-mounted package; 2 leads | SOD523 | |

4 Marking

Table 3. Marking code

| Type number | Marking code |
|-------------|-------------------|
| BAP51-02 | K1 ^[1] |

^[1] The marking bar indicates the cathode (see simplified outline graphic in <u>Table 1</u>).

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|----------------------------|-------------------------|-----|------|------|
| V_R | continuous reverse voltage | | - | 60 | V |
| IF | continuous forward current | | - | 50 | mA |
| P _{tot} | total power dissipation | T _{sp} ≤ 90 °C | - | 715 | mW |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| Tj | junction temperature | | -65 | +150 | °C |

6 Thermal characteristics

Table 5. Thermal characteristics

| Symbol | Parameter | Conditions | Тур | Unit |
|-----------------------|--|------------|-----|------|
| R _{th(j-sp)} | thermal resistance from junction to solder point | | 85 | K/W |

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General purpose PIN diode

7 Characteristics

Table 6. Characteristics

 T_i = 25 °C unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|----------------|--------------------------|----------------------------------|-------|------|------|------|
| V _F | forward voltage | I _F = 50 mA | - | 0.95 | 1.1 | V |
| V _R | reverse voltage | I _R = 10 μA | 50 | - | - | V |
| I _R | reverse current | V _R = 50 V | - | - | 100 | nA |
| C _d | diode capacitance | f = 1 MHz (see <u>Figure 1</u>) | | · | | |
| | | V _R = 0 V | - | 0.4 | - | pF |
| | | V _R = 1 V | - | 0.3 | 0.55 | pF |
| | | V _R = 5 V | - | 0.2 | 0.35 | pF |
| r _D | diode forward resistance | f = 100 MHz (see Figure 2) | | ' | | |
| | | I _F = 0.5 mA | [1] - | 5.5 | 9 | Ω |
| | | I _F = 1 mA | [1] - | 3.6 | 6.5 | Ω |
| | | I _F = 10 mA | [1] | 1.5 | 2.5 | Ω |

^[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

General purpose PIN diode

8 Graphical data

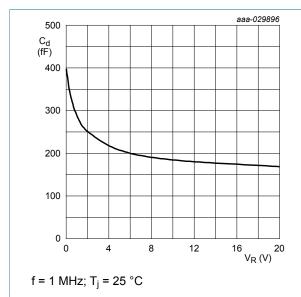


Figure 1. Diode capacitance as a function of reverse voltage (typical values)

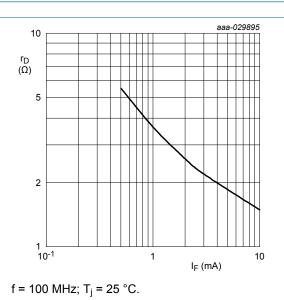
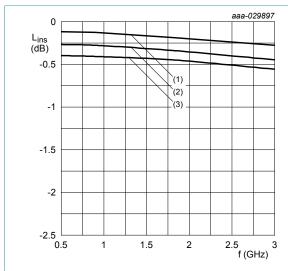


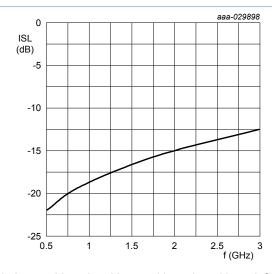
Figure 2. Diode forward resistance as a function of forward current (typical values)



Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer T-network; T_{amb} = 25 $^{\circ}C$

- (1) $I_F = 10 \text{ mA}$
- (2) $I_F = 1 \text{ mA}$
- (3) $I_F = 0.5 \text{ mA}$

Figure 3. Insertion loss of the diode in on-state as a function of frequency (typical values)

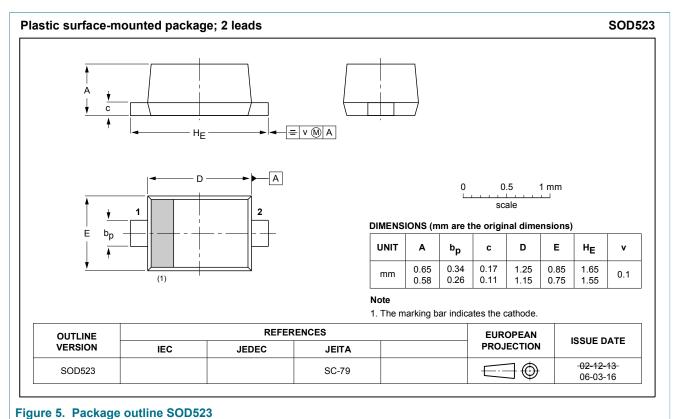


Diode zero-biased and inserted in series with a 50 Ω strip line circuit; T_{amb} = 25 $^{\circ}C$

Figure 4. Isolation of the diode in off-state as a function of frequency (typical values)

General purpose PIN diode

9 Package outline



rigure 5. Fackage outline 50Ds

surface-mounted device

10 Abbreviations

Table 7. Abbreviations

| Acronym | Description |
|---------|----------------------------|
| AQL | acceptable quality level |
| PIN | P-type, intrinsic, N-type |
| RF | radio frequency |
| S4 | special inspection level 4 |

SMD

General purpose PIN diode

11 Revision history

Table 8. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes | |
|----------------|----------------|--|---------------|--------------|--|
| BAP51-02 v.4 | 20181126 | Product data sheet | - | BAP51-02 v.3 | |
| Modifications: | The "Legal inf | Section 1.2 "Features and benefits has been updated. The "Legal information" pages have been updated. In table Limiting values description with V_R is changed from forward into reverse | | | |
| BAP51-02 v.3 | 20080102 | Product data sheet | - | - | |

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12 Legal information

12.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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